

PS7122A-1A,-2A,PS7122AL-1A,-2A**6, 8-PIN DIP, 250 V BREAK DOWN VOLTAGE
1-ch, 2-ch Optical Coupled MOS FET****DESCRIPTION**

The PS7122A-1A, -2A and PS7122AL-1A, -2A are solid state relays containing GaAs LEDs on the light emitting side (input side) and MOS FETs on the output side.

They are suitable for analog signal control because of their low offset and high linearity.

The PS7122AL-1A, -2A have a surface mount type lead.

FEATURES

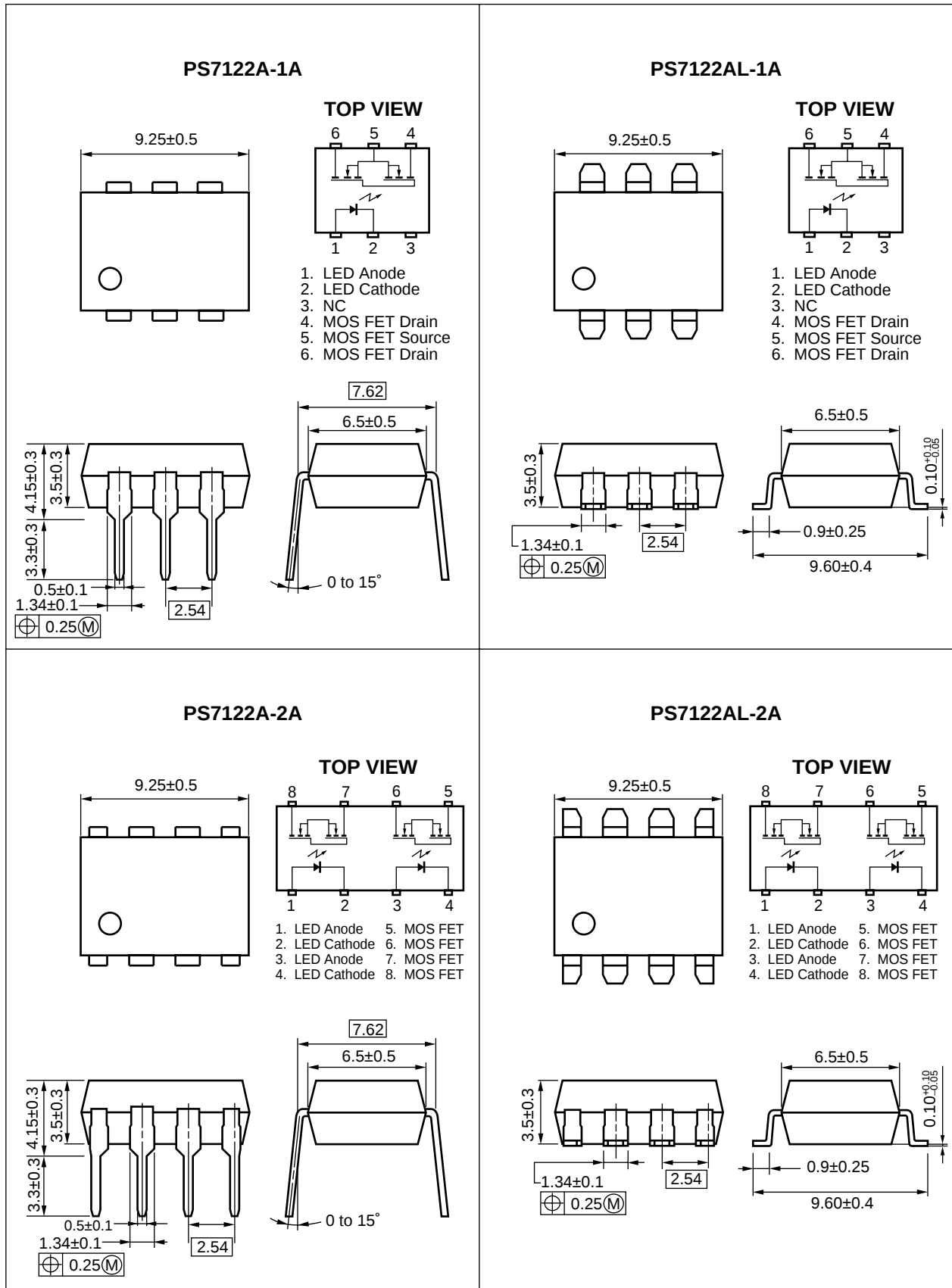
- 1 channel type (1 a output) or 2 channel type (1 a + 1 a output)
- Low LED operating current ($I_F = 2 \text{ mA}$)
- Designed for AC/DC switching line changer
- Small package (6, 8-pin DIP)
- Low offset voltage
- PS7122AL-1A, -2A: Surface mount type
- UL approved: File No. E72422 (S)
- BSI approved: No. 8245/8246
- CSA approved: No. CA 101391

APPLICATIONS

- Exchange equipment
- Measurement equipment
- FA/OA equipment

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Not all devices/types available in every country. Please check with local NEC Compound Semiconductor Devices representative for availability and additional information.

PACKAGE DIMENSIONS (in millimeters)



ORDERING INFORMATION

Part Number	Package	Packing Style	Application Part Number ^{*1}
PS7122A-1A	6-pin DIP	Magazine case 50 pcs	PS7122A-1A
PS7122AL-1A		Embossed Tape 1 000 pcs/reel	PS7122AL-1A
PS7122AL-1A-E3			
PS7122AL-1A-E4			
PS7122A-2A	8-pin DIP	Magazine case 50 pcs	PS7122A-2A
PS7122AL-2A		Embossed Tape 1 000 pcs/reel	PS7122AL-2A
PS7122AL-2A-E3			
PS7122AL-2A-E4			

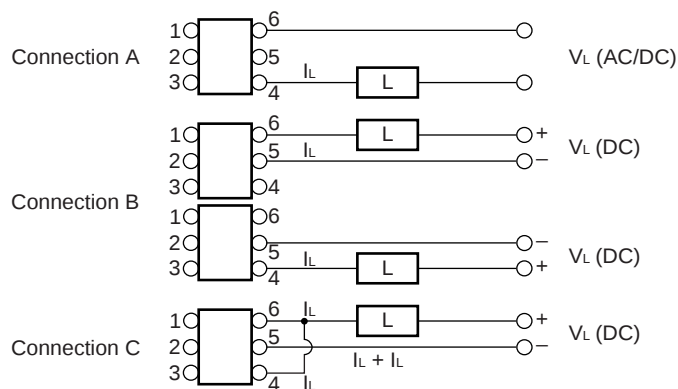
*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

Parameter		Symbol	Ratings		Unit
			PS7122A-1A, PS7122AL-1A	PS7122A-2A, PS7122AL-2A	
Diode	Forward Current (DC)	I_F	50		mA
	Reverse Voltage	V_R	5.0		V
	Power Dissipation	P_D	50		mW/ch
	Peak Forward Current ^{*1}	I_{FP}	1		A
MOS FET	Break Down Voltage	V_L	250		V
	Continuous Load Current ^{*2}	Connection A	200		mA
		Connection B	350	—	
		Connection C	500	—	
	Pulse Load Current ^{*3} (AC/DC Connection)	I_{LP}	400		mA
	Power Dissipation	P_D	560	375	mW/ch
Isolation Voltage ^{*4}		BV	1 500		Vr.m.s.
Total Power Dissipation		P_T	610	850	mW
Operating Ambient Temperature		T_A	-40 to +85		$^{\circ}\text{C}$
Storage Temperature		T_{stg}	-40 to +100		$^{\circ}\text{C}$

***1** PW = 100 μs , Duty Cycle = 1 %

***2** Conditions: $I_F \geq 2\text{ mA}$. The following types of load connections are available.



***3** PW = 100 ms, 1 shot

***4** AC voltage for 1 minute at $T_A = 25\text{ }^{\circ}\text{C}$, RH = 60 % between input and output

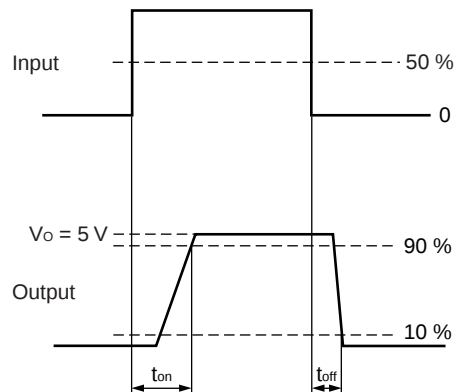
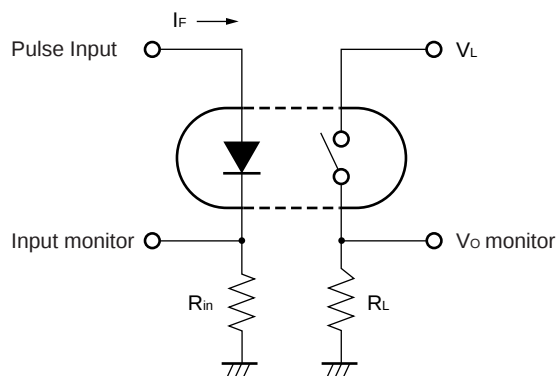
RECOMMENDED OPERATING CONDITIONS ($T_A = 25\text{ }^{\circ}\text{C}$)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	I_F	2	10	20	mA
LED Off Voltage	V_F	0		0.5	V

ELECTRICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$)

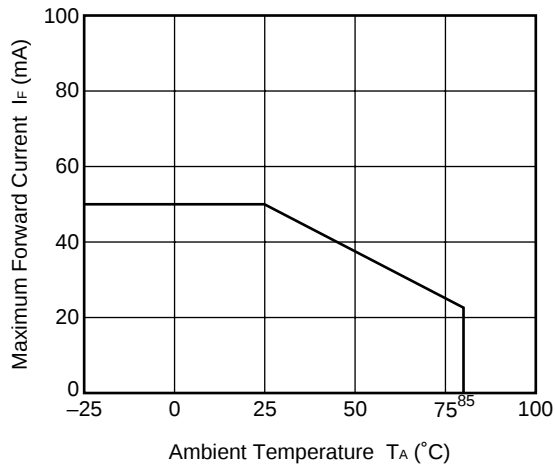
Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V_F	$I_F = 10\text{ mA}$		1.2	1.4	V
	Reverse Current	I_R	$V_R = 5\text{ V}$			5.0	μA
MOS FET	Off-state Leakage Current	I_{Leak}	$V_D = 250\text{ V}$		0.03	1.0	μA
	Output Capacitance	C_{out}	$V_D = 0\text{ V}$, $f = 1\text{ MHz}$		120		pF/ch
Coupled	LED On-state Current	I_{Fon}	$I_L = 200\text{ mA}$			2.0	mA
	On-state Resistance	R_{on1}	$I_F = 10\text{ mA}$, $I_L = 10\text{ mA}$		4.5	8.0	Ω
		R_{on2}	$I_F = 10\text{ mA}$, $I_L = 200\text{ mA}$, $t \leq 10\text{ ms}$				
	Turn-on Time ^{*1}	t_{on}	$I_F = 10\text{ mA}$, $V_O = 5\text{ V}$, $R_L = 500\text{ }\Omega$, $PW \geq 10\text{ ms}$		0.5	1.5	ms
	Turn-off Time ^{*1}	t_{off}			0.04	0.2	
	Isolation Resistance	$R_{\text{I-O}}$	$V_{\text{I-O}} = 1.0\text{ kV}_{\text{DC}}$	10^9			Ω
	Isolation Capacitance	$C_{\text{I-O}}$	$V = 0\text{ V}$, $f = 1\text{ MHz}$		1.1		pF/ch

*1 Test Circuit for Switching Time

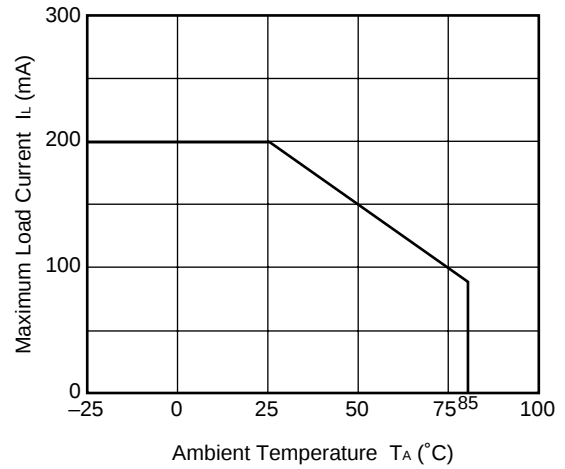


★ TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

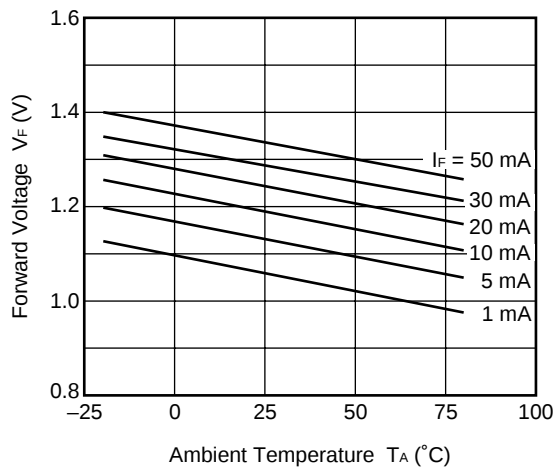
MAXIMUM FORWARD CURRENT vs. AMBIENT TEMPERATURE



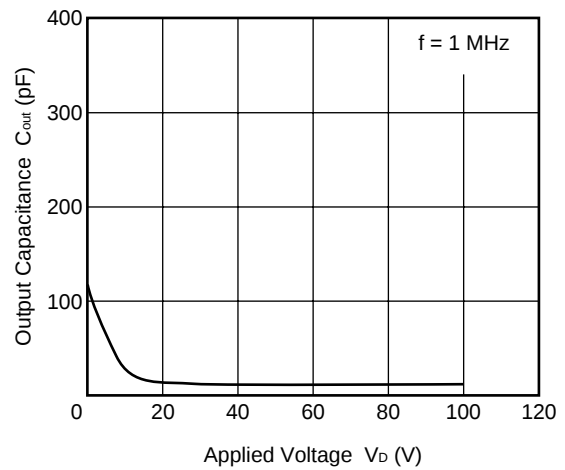
MAXIMUM LOAD CURRENT vs. AMBIENT TEMPERATURE



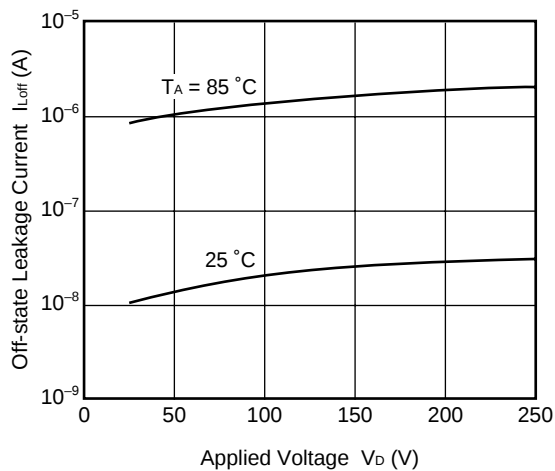
FORWARD VOLTAGE vs. AMBIENT TEMPERATURE



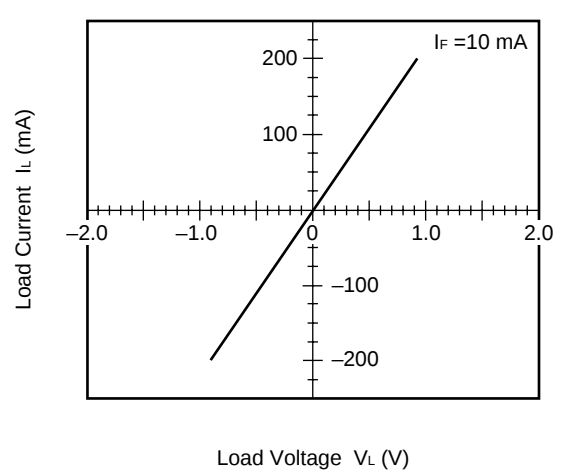
OUTPUT CAPACITANCE vs. APPLIED VOLTAGE



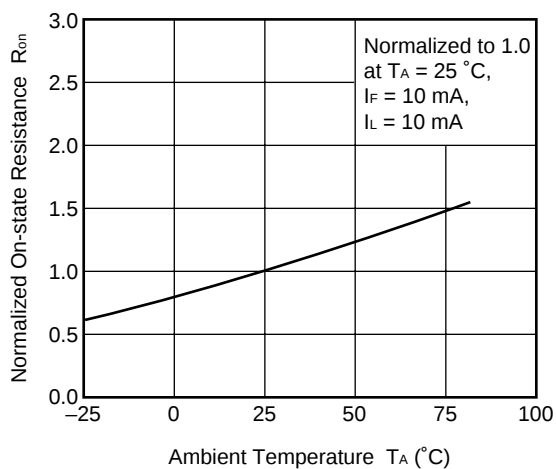
OFF-STATE LEAKAGE CURRENT vs. APPLIED VOLTAGE



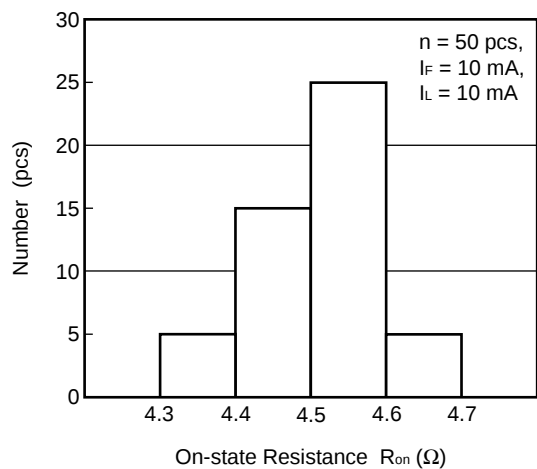
LOAD CURRENT vs. LOAD VOLTAGE



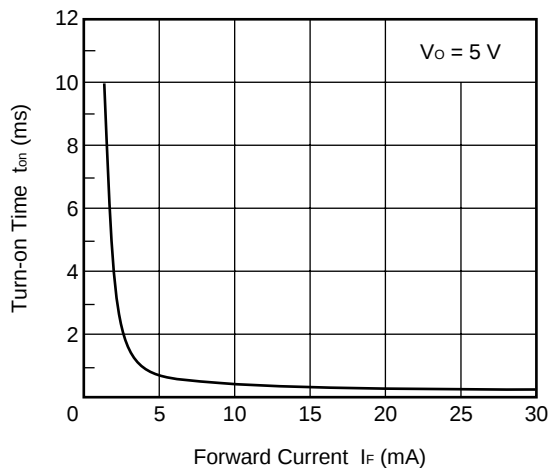
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



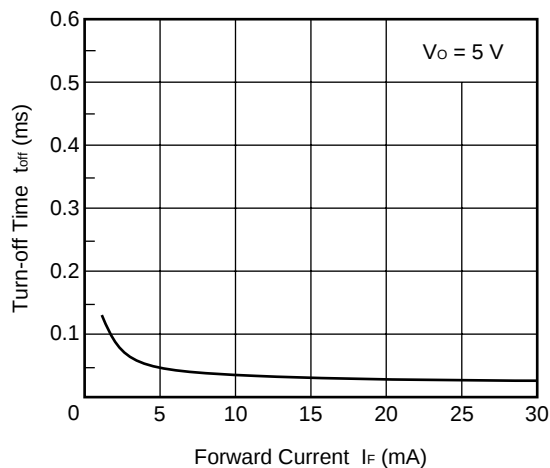
ON-STATE RESISTANCE DISTRIBUTION



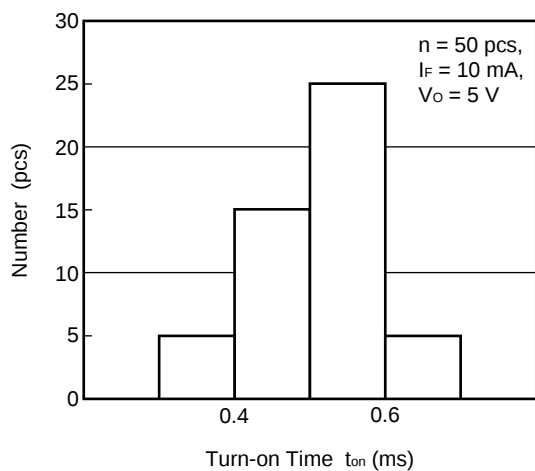
TURN-ON TIME vs. FORWARD CURRENT



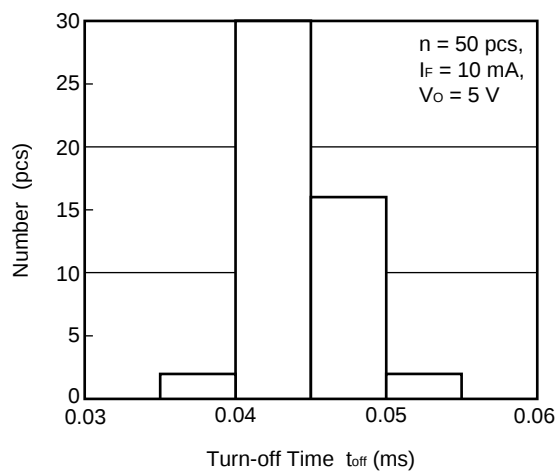
TURN-OFF TIME vs. FORWARD CURRENT

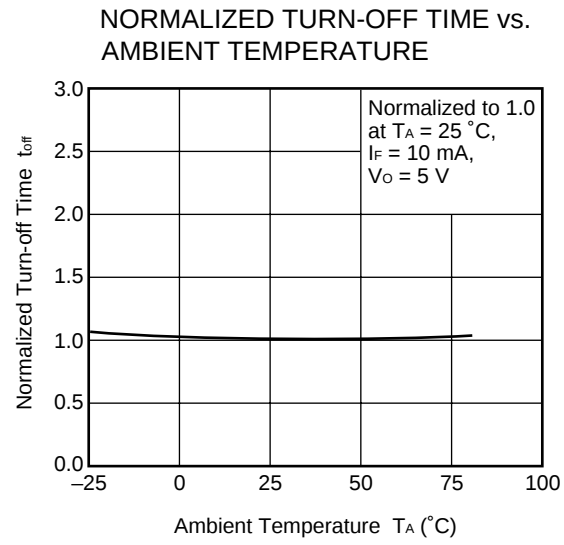
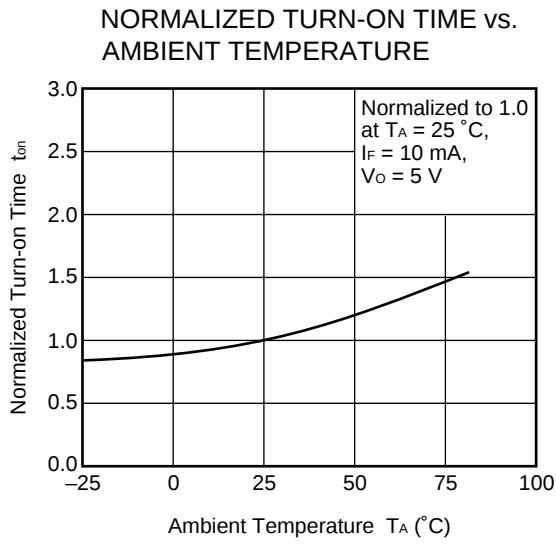


TURN-ON TIME DISTRIBUTION



TURN-OFF TIME DISTRIBUTION

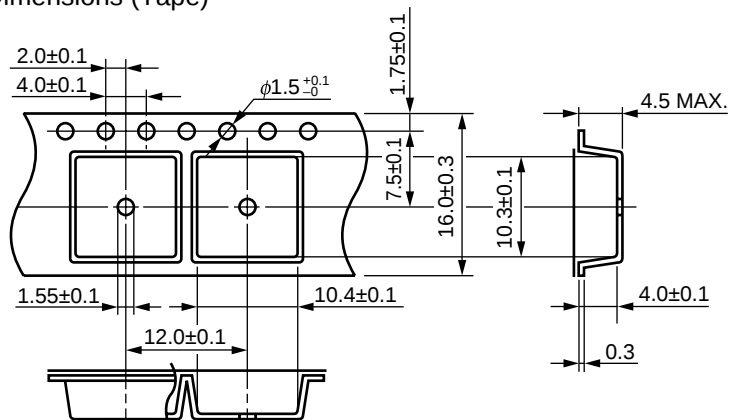




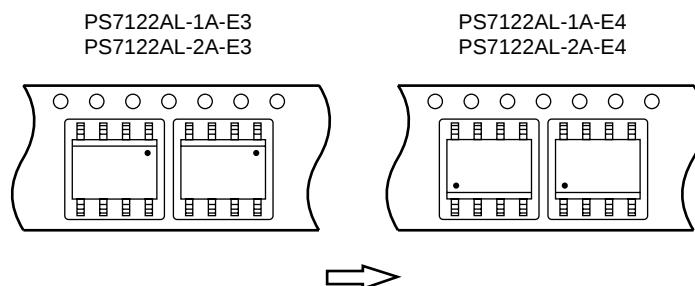
Remark The graphs indicate nominal characteristics.

★ TAPING SPECIFICATIONS (in millimeters)

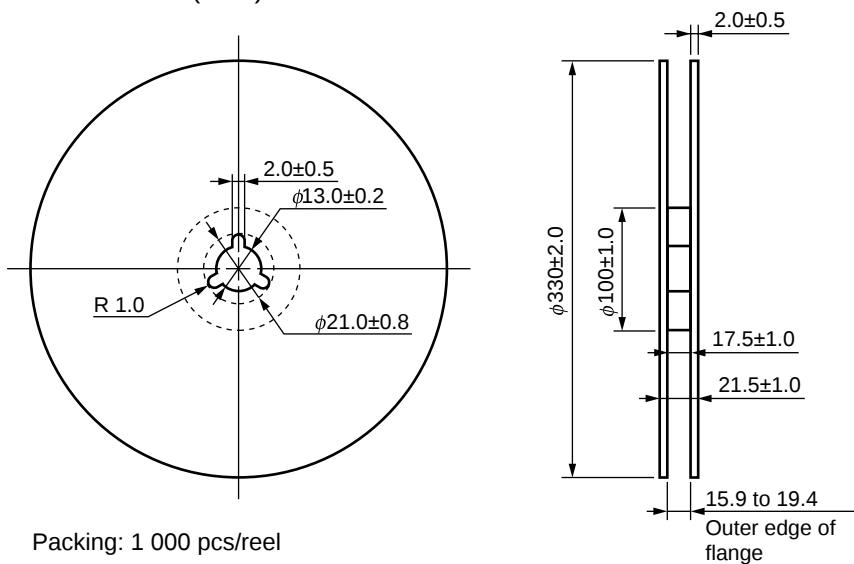
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)

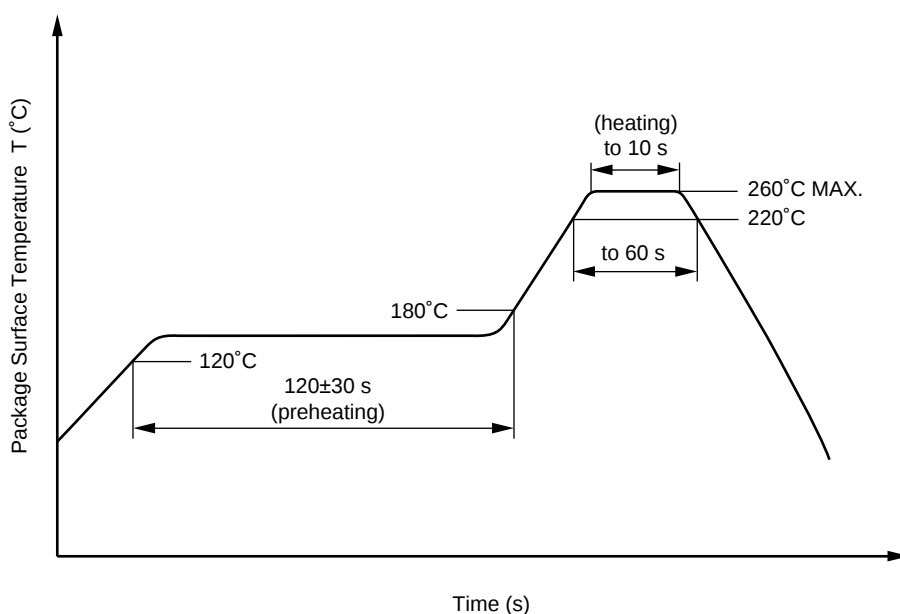


★ **RECOMMENDED SOLDERING CONDITIONS**

(1) Infrared reflow soldering

- | | |
|---|--|
| • Peak reflow temperature | 260°C or below (package surface temperature) |
| • Time of peak reflow temperature | 10 seconds or less |
| • Time of temperature higher than 220°C | 60 seconds or less |
| • Time to preheat temperature from 120 to 180°C | 120±30 s |
| • Number of reflows | Three |
| • Flux | Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- | | |
|-------------------------|--|
| • Temperature | 260°C or below (molten solder temperature) |
| • Time | 10 seconds or less |
| • Preheating conditions | 120°C or below (package surface temperature) |
| • Number of times | One |
| • Flux | Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

(3) Cautions

- Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

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M8E 00.4-0110

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Caution GaAs Products	The product contains gallium arsenide, GaAs. GaAs vapor and powder are hazardous to human health if inhaled or ingested. • Do not destroy or burn the product. • Do not cut or cleave off any part of the product. • Do not crush or chemically dissolve the product. • Do not put the product in the mouth. Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.
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►For further information, please contact

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